

8th International Meeting on Front-End Electronics

Tuesday, 24 May 2011

3D/Vertical Integration and Advanced Interconnections - Aula 3 (14:30 - 16:00)

time	[id] title	presenter
14:30	[34] 3D CMOS submission	Mr YAREMA, Ray
15:00	[35] CMC-CMP-MOSIS collaboration for a 3D-IC prototyping service	TORKI, Kholdoun
15:30	[36] Interconnection technology and TSVs for ATLAS pixels in the ICV-SLID process	MOSER, Hans-Günther

3D/Vertical Integration and Advanced Interconnections - Aula 3 (16:30 - 18:30)

time	[id] title	presenter
16:30	[37] 3D ASIC prototyping and plans with EMFT	SELLER, Paul
17:00	[38] Advanced CMOS-based pixel sensors	DE MOOR, Piet
17:30	[49] Analog front-ends for monolithic and hybrid pixels developed with a 3D CMOS process	ZUCCA, Stefano
18:00	[16] 2D MAPS in the Tezzaron/Chartered technology	Dr PASSERI, Daniele